



SDI FINAL EVALUATION FORM 1.1

PART 1:

Journal Name:	Journal of Materials Science Research and Reviews
Manuscript Number:	Ms_JMSRR_43485
Title of the Manuscript:	Si Microwire Anode with Enhanced Conductivity through Decoration with Cu Nanoparticles
Type of Article:	Original Research Article

PART 2:

FINAL EVALUATOR'S comments on revised paper (if any)	Authors' response to final evaluator's comments
1. TEM should be provided. 2. Near half of references belong to self-citation. 3. Compared with the author's work in Electrochim. Acta, 101, 93 (2013) and J. Electrochem. Soc., 158, E119 (2011), there is no new development about Si microwire anode.	1. Dear reviewer, thanks for your comment. Nevertheless, we do not see how TEM may enhance the quality of the paper. The preparation procedure to analyze Si microwires in TEM is complicated, and is just achievable with FIB slicing. In conclusion: The observation under TEM is not direct, we do not gain any additional info, and we do not have access to that equipment. 2. You are right, a lot of references are about our work. However, it is justified... The work is about Si microwire arrays that nobody else produces. The work is about enhancing the properties of the anodes that we produce in our research group. Even though, a reference has now been added for explaining crack formation in Si wires with constraint volume expansion. 3. You are partially right. There is no new development about the production of the Si microwire array. However, the paper is not about the production of the wires, but about the decoration of the Si wires with Cu particles to enhance their electronic transport, and their charging/discharging rate capability as a consequence.